

Product Summary

BV_{DSS}	$R_{DS(ON)}$ max	I_D max $T_A = +25^\circ\text{C}$
30V	21m Ω @ $V_{GS} = 10\text{V}$	10A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- General Purpose Interfacing Switch
- Power Management Functions
- DC-DC Converters
- Analog Switch

Features and Benefits

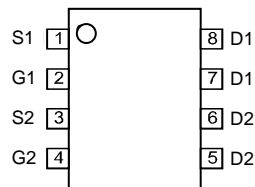
- Low On-Resistance
- Low Input Capacitance
- Low Input/Output Leakage
- Low Gate Resistance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

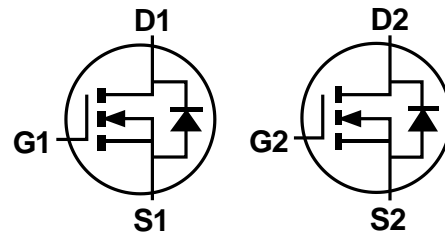
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish – Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ^(e3)
- Weight: 0.072 grams (Approximate)



Top View



Top View
Internal Schematic



N-Channel MOSFET

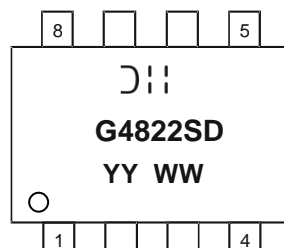
N-Channel MOSFET

Ordering Information (Note 5)

Part Number	Case	Packaging
DMG4822SSDQ-13	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to <https://www.diodes.com/quality/product-compliance-definitions/>.
 5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



DII = Manufacturer's Marking
 G4822SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 17 = 2017)
 WW = Week (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	30	V	
Gate-Source Voltage	V_{GSS}	± 25	V	
Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$	10	A
		$T_A = +85^\circ\text{C}$	6.6	A
Pulsed Drain Current (Note 7)	I_{DM}	60	A	
Avalanche Current (Notes 8 & 9)	I_{AR}	1.68	A	
Repetitive Avalanche Energy, $L = 0.3\text{mH}$ (Notes 8 & 9)	E_{AR}	12.8	mJ	

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P_D	1.42	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	88.4	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 10)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 25\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 10)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	—	3	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	13.4	21	m Ω	$V_{GS} = 10\text{V}, I_D = 8.5\text{A}$
		—	19.5	32.5		$V_{GS} = 4.5\text{V}, I_D = 6\text{A}$
Forward Transfer Admittance	$ Y_{fs} $	—	20	—	mS	$V_{DS} = 5\text{V}, I_D = 8.5\text{A}$
Diode Forward Voltage	V_{SD}	—	0.4	1.0	V	$V_{GS} = 0\text{V}, I_S = 1\text{A}$
DYNAMIC CHARACTERISTICS (Note 11)						
Input Capacitance	C_{iss}	—	478.9	—	pF	$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	96.7	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	61.4	—	pF	
Gate Resistance	R_g	—	1.1	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_g	—	5	—	nC	$V_{GS} = 10\text{V}, V_{DS} = 15\text{V}, I_D = 8.5\text{A}$
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	—	10.5	—	nC	
Gate-Source Charge	Q_{gs}	—	1.8	—	nC	
Gate-Drain Charge	Q_{gd}	—	1.6	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	2.9	—	ns	$V_{DS} = 15\text{V}, V_{GS} = 10\text{V}, R_L = 1.8\Omega, R_G = 3\Omega$
Turn-On Rise Time	t_R	—	7.9	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	14.6	—	ns	
Turn-Off Fall Time	t_F	—	3.1	—	ns	

- Notes:
6. Device mounted on FR-4 PCB, with minimum recommended pad layout.
 7. Device mounted on minimum recommended pad layout test board, 10 μs pulse duty cycle = 1%.
 8. Repetitive rating, pulse width limited by junction temperature.
 9. I_{AR} and E_{AR} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.
 10. Short duration pulse test used to minimize self-heating effect.
 11. Guaranteed by design. Not subject to product testing.

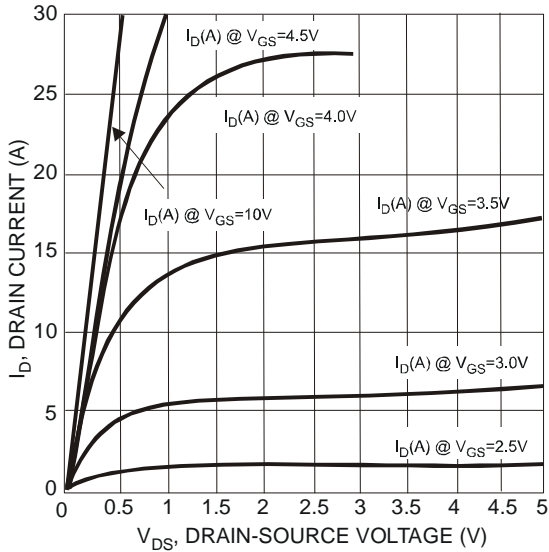


Fig.1 Typical Output Characteristic

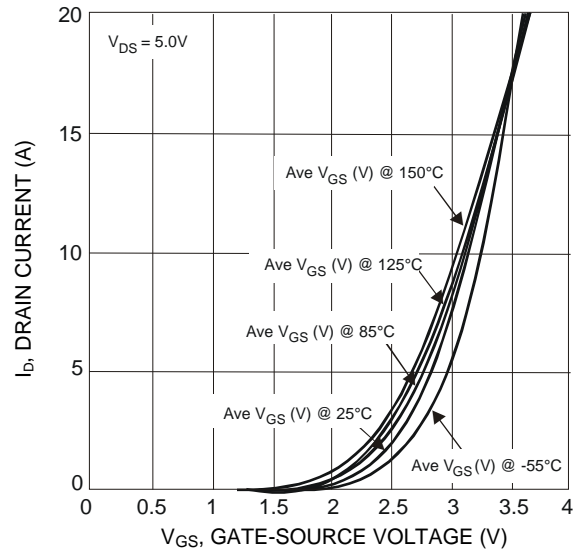


Fig.2 Typical Transfer Characteristics

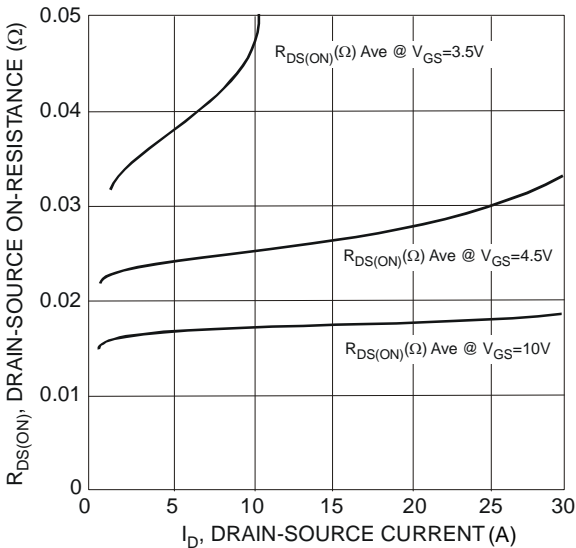


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

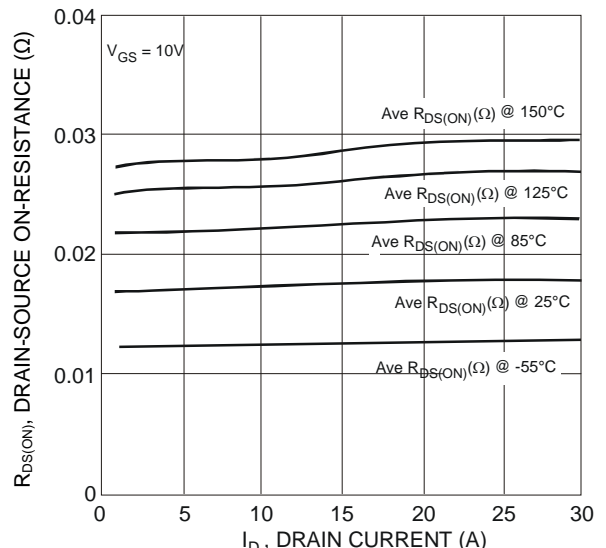


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

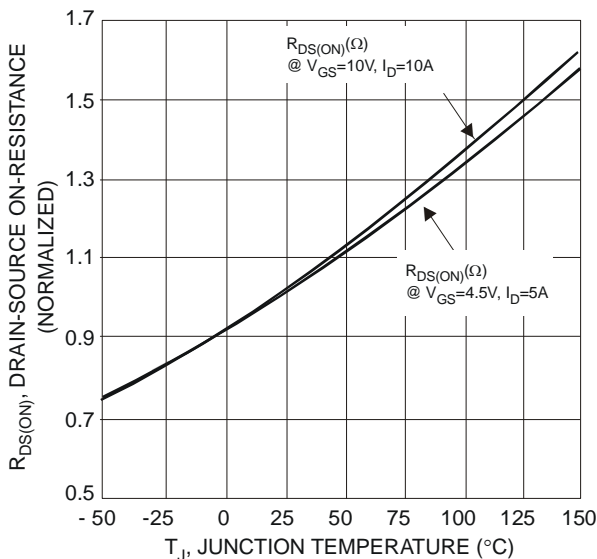


Fig. 5 On-Resistance Variation with Temperature

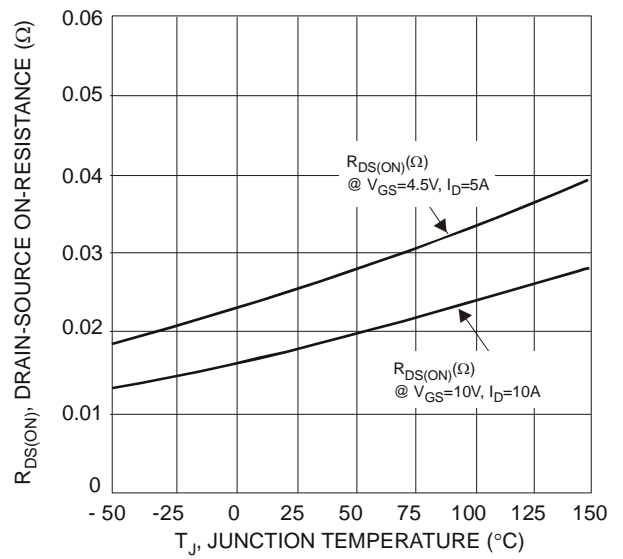


Fig. 6 On-Resistance Variation with Temperature

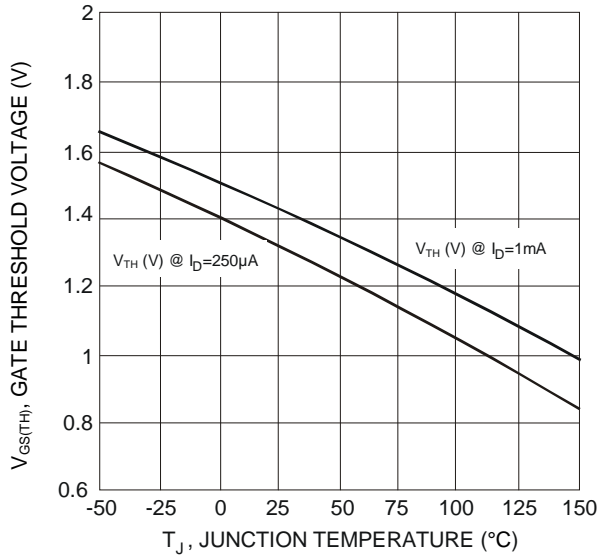


Fig. 7 Gate Threshold Variation vs. Junction Temperature

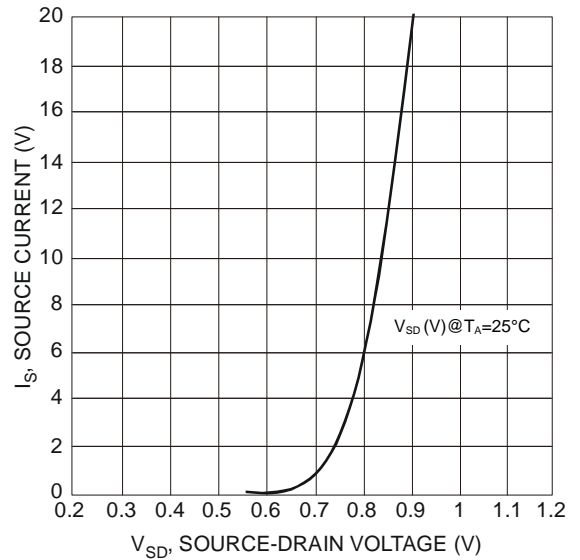


Fig.8 Diode Forward Voltage vs. Current

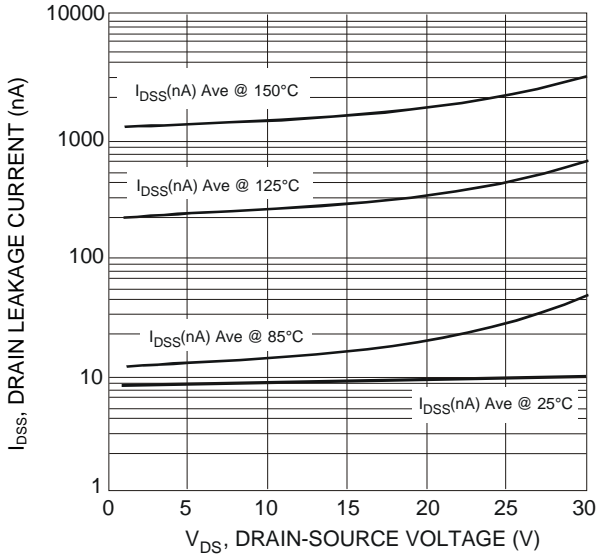


Fig. 9 Typical Drain-Source Leakage Current vs. Voltage

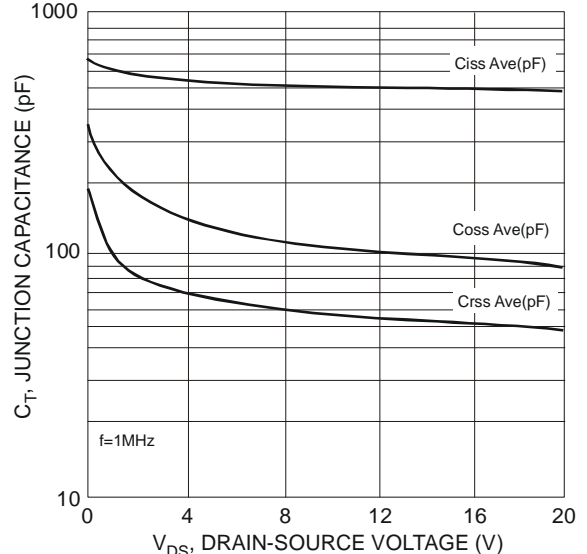


Fig. 10 Typical Junction Capacitance

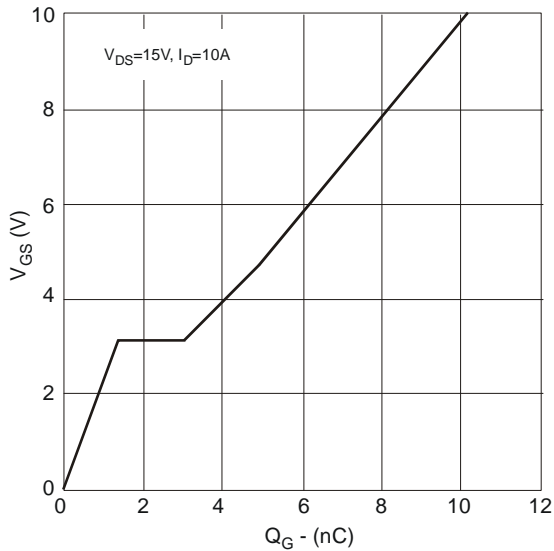
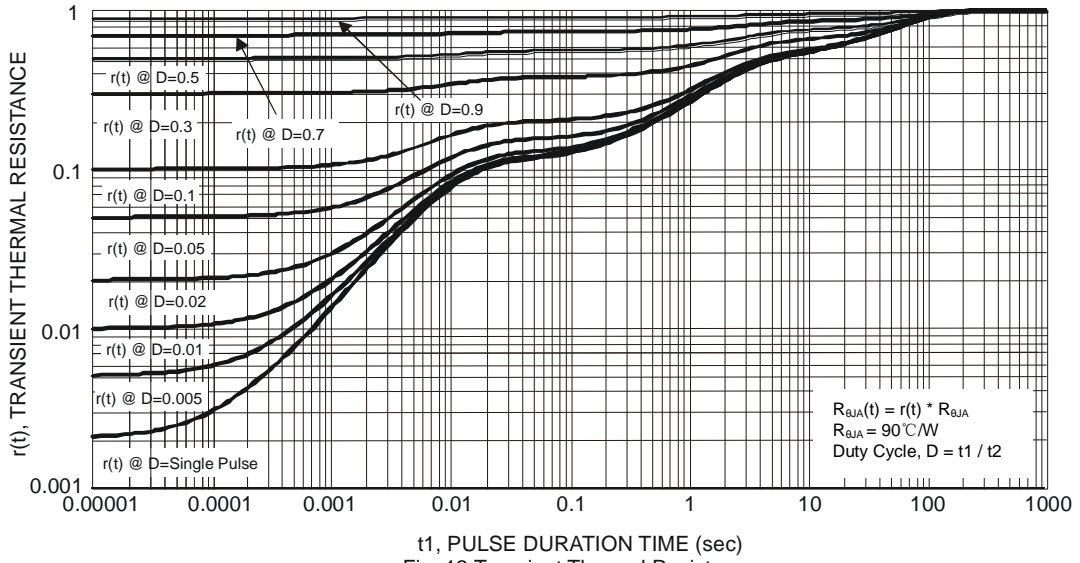


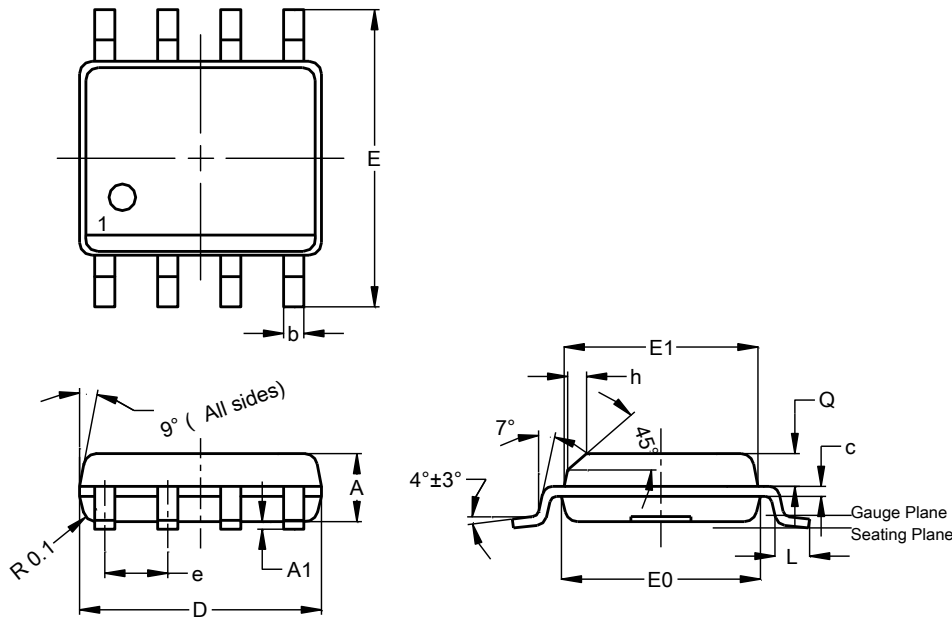
Fig. 11 Gate Charge



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



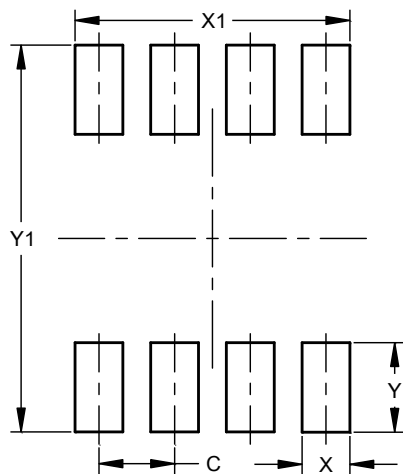
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Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	-	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

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